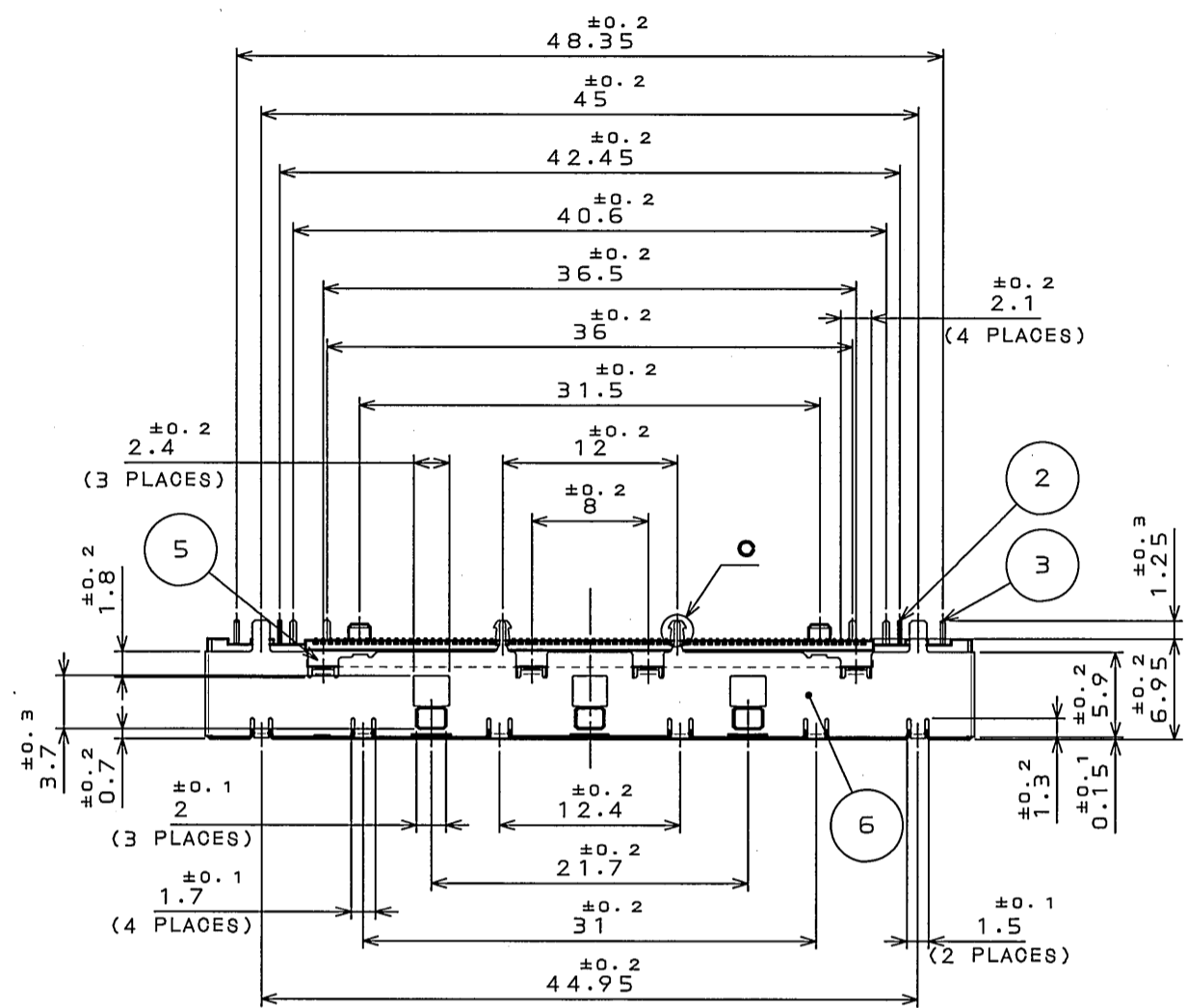
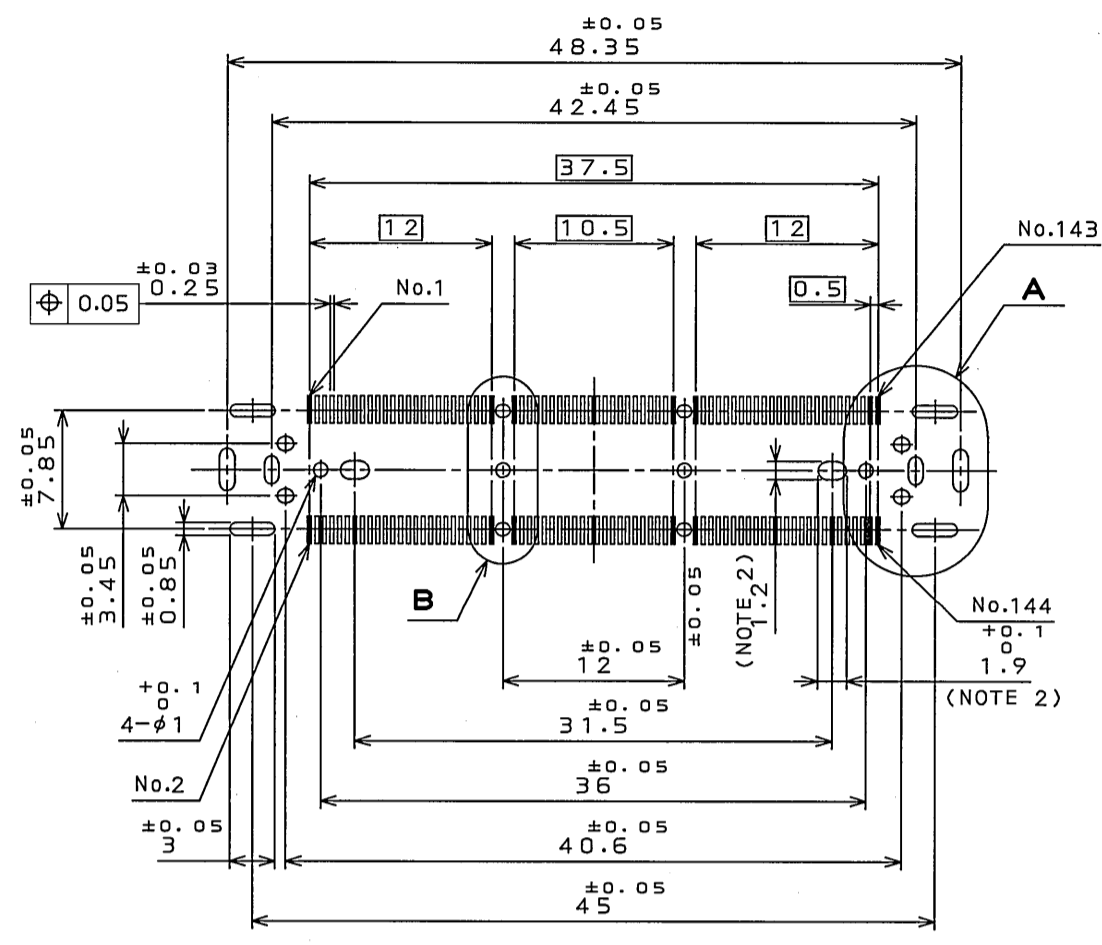
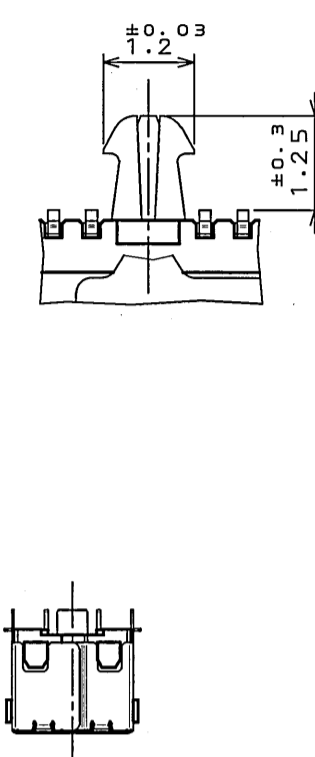


9LE8376 SJ108376
('ON 8NIMV8H)各量理図

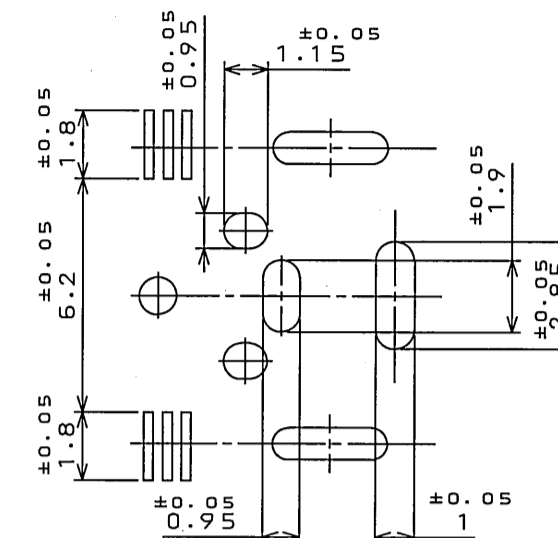
版数 REV.	年月日 DATE	DON NO.	変更内容 DESCRIPTION	製図 DR.	担当 CHK.	査閲 APPD.	承認 APPD.
2	20.Nov.2008	066659	REVISED TAPE DIMENSION		M.SASAKI		K.Hisatomi



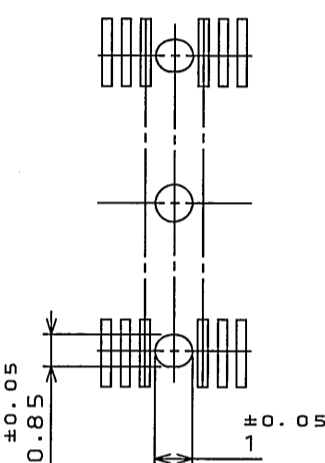
DETAIL C
(SCALE 10:1)



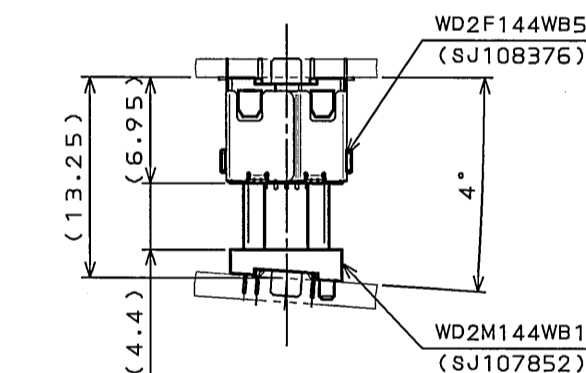
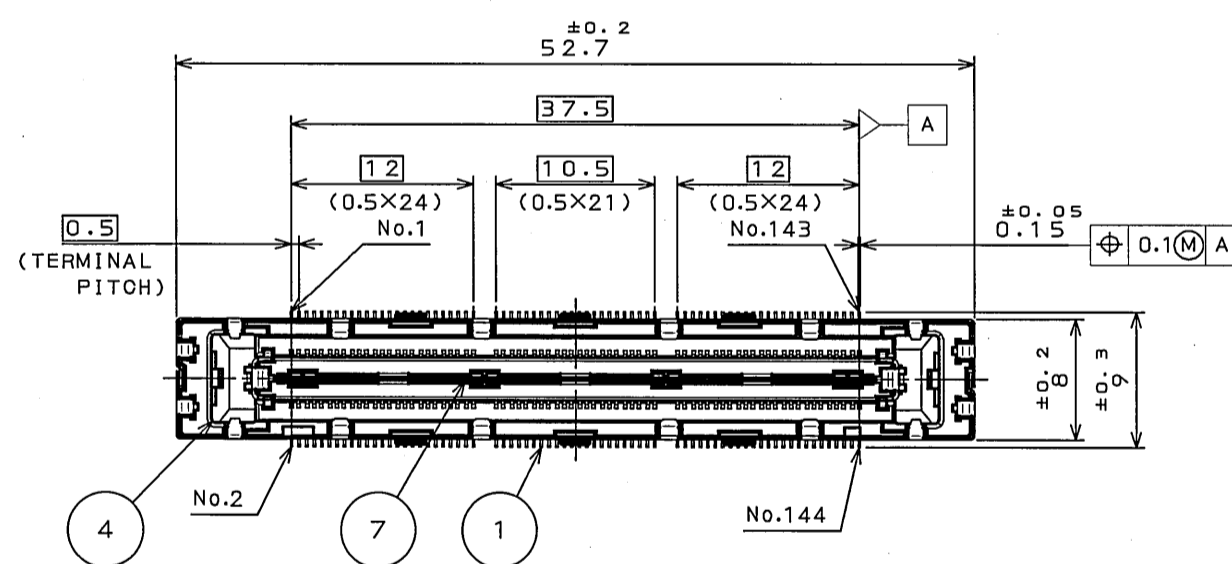
APPLICABLE P.C.B. DIMENSION (REF.)
適合基板寸法 (参考)



DETAIL A
(SCALE 5:1)



DETAIL B
(SCALE 5:1)



MATED CONDITION (REF.)
嵌合状態図 (参考)

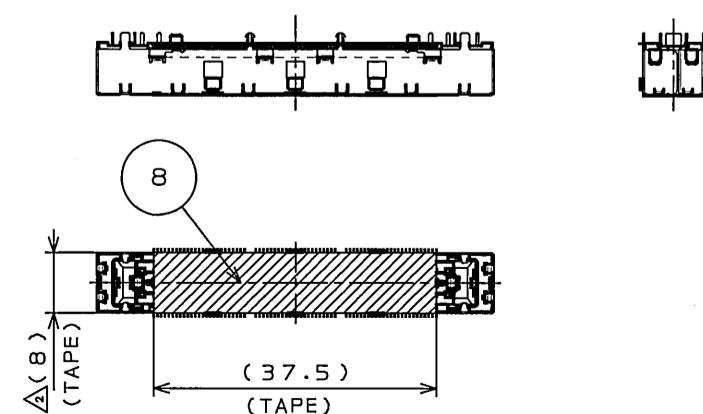
TABLE 1

	SIGNAL CONTACT 信号コンタクト	POWER CONTACT #1 & #2 電源コンタクト #1
CONTACT AREA 接触部	GOLD(0.3 μ m MIN.) OVER NICKEL NI上Au 0.3 μ m以上	GOLD(0.3 μ m MIN.) OVER NICKEL NI上Au 0.3 μ m以上
SOLDERING AREA 半田付部	GOLD FLASH OVER NICKEL NI上Auフラッシュ	TIN PLATING OVER NICKEL Ni上Sn

8	TAPE	1	HEAT-RESISTANT TAPE		
7	PLATE	1	COPPER ALLOY	TIN PLATING	
6	SHELL	2	COPPER ALLOY	NICKEL PLATING	
5	INNER INSULATOR	2	GLASS FILLED LCP		UL94V-0 COLOR:BLACK
4	INSULATOR	1	GLASS FILLED LCP		UL94V-0 COLOR:BLACK
3	POWER CONTACT #2	2	COPPER ALLOY	TABLE 1	
2	POWER CONTACT #1	2	COPPER ALLOY	TABLE 1	
1	SIGNAL CONTACT	144	COPPER ALLOY	TABLE 1	
符号 NO.	名称 DESCRIPTION	個数 QTY.	材料 MATERIAL	仕上 FINISH	備考 REMARKS

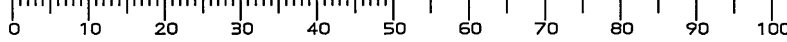
仕様書 (SPECIFICATION)		第1版 (ORIGINAL DATE) 14.Mar.2008		尺度 (SCALE) 2:1	シリーズ (SERIES) WD2	製図 DR. M.SASAKI	名称 (TITLE) WD2F144WB5	承認 CHK. M.SASAKI	日本航空電子工業株式会社 JAPAN AVIATION ELECTRONICS INDUSTRY, LTD.	
公差 (GENERAL TOLERANCE)		承認 APPD. K.HISATOMI		(HEIGHT: 6.95mm)		承認 APPD.		図面番号 (DRAWING NO.) SJ108376		版数 (REV.) 2

NOTE 1. TERMINAL COPLANARITY IS 0.1mm MAX.
NOTE 2. ALL HOLES, EXCEPT FOR HOLES AS SHOWN, NEED TO BE THROUGH-HOLE PLATING.
注1. 端子平坦度は0.1mm以下
注2. 図示の穴以外の穴は、スルーホールめっきを施すこと。



TAPE ATTACHED CONDITION
テープ貼り付け状態図

DOF-0-213F(05.08)



SIZE A2

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